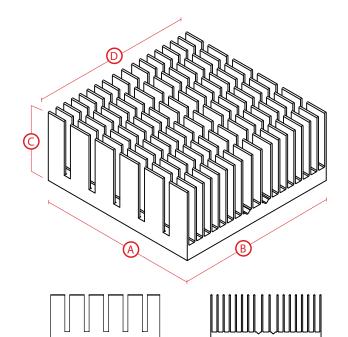


High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

ATS PART # ATS-55330W-C2-R0

Features & Benefits

- » High efficiency cross-cut fin design provides low pressure drop characteristics
- » Large surface area increases heat sink performance
- » Designed for BGAs and surface mount packages
- » Comes preassembled with high performance thermal interface material



*Image above is for illustration purposes only

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE				
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)			
200	1.0	3.4	NA			
300	1.5	NA				
400	2.0	NA				
500	2.5	NA				
600	3.0	NA				
700	3.5	NA				
800	4.0	NA				

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
33 mm	33 mm	24.5 mm	33 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

2) Thermal performance data are provided for reference only. Actual performance may vary

by application.ATS reserves the right to update or change its products without notice to improve the design or performance.

Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).